# **General Description**

The MAX9123 quad low-voltage differential signaling (LVDS) differential line driver is ideal for applications requiring high data rates, low power, and low noise. The MAX9123 is guaranteed to transmit data at speeds up to 800Mbps (400MHz) over controlled impedance media of approximately  $100\Omega$ . The transmission media may be printed circuit (PC) board traces, backplanes, or cables.

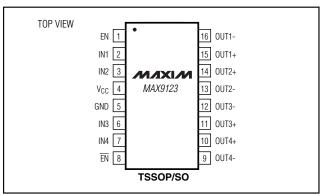
The MAX9123 accepts four LVTTL/LVCMOS input levels and translates them to LVDS output signals. Moreover, the MAX9123 is capable of setting all four outputs to a high-impedance state through two enable inputs, EN and EN, thus dropping the device to an ultra-low-power state of 16mW (typ) during high impedance. The enables are common to all four transmitters. Outputs conform to the ANSI TIA/EIA-644 LVDS standard. Flow-through pinout simplifies PC board layout and reduces crosstalk by separating the LVTTL/LVCMOS inputs and LVDS outputs.

The MAX9123 operates from a single +3.3V supply and is specified for operation from -40°C to +85°C. It is available in 16-pin TSSOP and SO packages. Refer to the MAX9121/MAX9122\* data sheet for quad LVDS line receivers with integrated termination and flow-through pinout.

### **Applications**

- Digital Copiers Laser Printers Cell Phone Base Stations Add Drop Muxes Digital Cross-Connects
- DSLAMs Network Switches/Routers Backplane Interconnect Clock Distribution

# **Pin Configuration**



\* Future product—contact factory for availability.

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Maxim Integrated Products 1

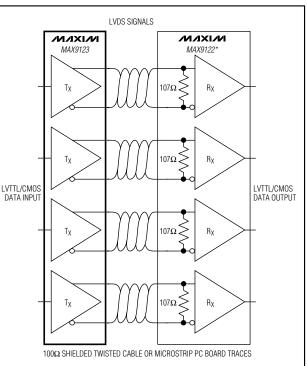
Features

- Flow-Through Pinout Simplifies PC Board Layout Reduces Crosstalk
- Pin Compatible with DS90LV047A
- Guaranteed 800Mbps Data Rate
- 250ps Maximum Pulse Skew
- ♦ Conforms to TIA/EIA-644 LVDS Standard
- Single +3.3V Supply
- ♦ 16-Pin TSSOP and SO Packages

### **Ordering Information**

PART	TEMP. RANGE	PIN-PACKAGE
MAX9123EUE	-40°C to +85°C	16 TSSOP
MAX9123ESE	-40°C to +85°C	16 SO

# **Typical Applications Circuit**



For price, delivery, and to place orders, please contact Maxim Distribution at 1-888-629-4642, or visit Maxim's website at www.maxim-ic.com.

## **ABSOLUTE MAXIMUM RATINGS**

V <sub>CC</sub> to GND	0.3V to +4.0V
IN_, EN, EN to GND	-0.3V to (V <sub>CC</sub> + 0.3V)
OUT_+, OUT to GND	0.3V to +3.9V
Short-Circuit Duration (OUT_+, OUT)	Continuous
Continuous Power Dissipation ( $T_A = +70^{\circ}C$	C)
16-Pin TSSOP (derate 9.4mW/°C above	
16-Pin SO (derate 8.7mW/°C above +70	)°C)696mW

Storage Temperature Range	65°C to +150°C
Maximum Junction Temperature	+150°C
Operating Temperature Range	
Lead Temperature (soldering, 10s)	+300°C
ESD Protection	
Human Body Model, IN, OUT +, OU	T±4kV

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

# DC ELECTRICAL CHARACTERISTICS

(V<sub>CC</sub> = +3.0V to +3.6V, R<sub>L</sub> = 100 $\Omega$  ±1%, T<sub>A</sub> = -40°C to +85°C. Typical values are at V<sub>CC</sub> = +3.3V, T<sub>A</sub> = +25°C, unless otherwise noted.) (Notes 1, 2)

PARAMETER	SYMBOL	CONDITIONS	MIN	ТҮР	MAX	UNITS
LVDS OUTPUT (OUT_+, OUT)						
Differential Output Voltage	V <sub>OD</sub>	Figure 1	250	368	450	mV
Change in Magnitude of V <sub>OD</sub> Between Complementary Output States	ΔV <sub>OD</sub>	Figure 1		1	35	mV
Offset Voltage	V <sub>OS</sub>	Figure 1	1.125	1.25	1.375	V
Change in Magnitude of V <sub>OS</sub> Between Complementary Output States	ΔV <sub>OS</sub>	Figure 1		4	25	mV
Output High Voltage	VOH				1.6	V
Output Low Voltage	V <sub>OL</sub>		0.90			V
Differential Output Short-Circuit Current (Note 3)	IOSD	Enabled, V <sub>OD</sub> = 0			-9	mA
Output Short-Circuit Current	I <sub>OS</sub>	OUT_+ = 0 at IN_ = V <sub>CC</sub> or OUT = 0 at IN_ = 0, enabled		-3.8	-9	mA
Output High-Impedance Current	I <sub>OZ</sub>	EN = low and $\overline{\text{EN}}$ = high, OUT_+ = 0 or V <sub>CC</sub> , OUT = 0 or V <sub>CC</sub> , R <sub>L</sub> = $\infty$	-10		10	μA
Power-Off Output Current	IOFF	V <sub>CC</sub> = 0 or open, OUT_+ = 0 or 3.6V, OUT = 0 or 3.6V, R <sub>L</sub> = ∞	-20		20	μA
INPUTS (IN_, EN, EN)						
High-Level Input Voltage	VIH		2.0		V <sub>CC</sub>	V
Low-Level Input Voltage	VIL		GND		0.8	V
Input Current	lin	IN_, EN, $\overline{EN} = 0$ or $V_{CC}$	-20		20	μA
SUPPLY CURRENT						
No-Load Supply Current	Icc	$R_L = \infty$ , $IN = V_{CC}$ or 0 for all channels		9.2	11	mA
Loaded Supply Current	ICCL	$R_L$ = 100 $\Omega$ , IN_ = V <sub>CC</sub> or 0 for all channels		22.7	30	mA
Disabled Supply Current	Iccz	Disabled, IN_ = $V_{CC}$ or 0 for all channels, EN = 0, $\overline{EN} = V_{CC}$		4.9	6	mA

# SWITCHING CHARACTERISTICS

 $(V_{CC} = +3.0V \text{ to } +3.6V, R_L = 100\Omega \pm 1\%, C_L = 15pF, T_A = -40^{\circ}C \text{ to } +85^{\circ}C.$  Typical values are at  $V_{CC} = +3.3V, T_A = +25^{\circ}C$ , unless otherwise noted.) (Notes 4, 5, 6)

PARAMETER	SYMBOL	OL CONDITIONS		ТҮР	МАХ	UNITS
Differential Propagation Delay High to Low	<sup>t</sup> PHLD	Figures 2 and 3			1.7	ns
Differential Propagation Delay Low to High	tPLHD	Figures 2 and 3			1.7	ns
Differential Pulse Skew (Note 7)	tskD1	Figures 2 and 3		0.04	0.25	ns
Differential Channel-to-Channel Skew (Note 8)	tskd2	Figures 2 and 3		0.07	0.35	ns
Differential Part-to-Part Skew (Note 9)	tskd3	Figures 2 and 3		0.13	0.8	ns
Differential Part-to-Part Skew (Note 10)	t <sub>SKD4</sub>	Figures 2 and 3		0.43	1.0	ns
Rise Time	t <sub>TLH</sub>	Figures 2 and 3	0.2	0.39	1.0	ns
Fall Time	t <sub>THL</sub>	Figures 2 and 3	0.2	0.39	1.0	ns
Disable Time High to Z	t <sub>PHZ</sub>	Figures 4 and 5		2.7	5	ns
Disable Time Low to Z	<b>t</b> PLZ	Figures 4 and 5		2.7	5	ns
Enable Time Z to High	t <sub>PZH</sub>	Figures 4 and 5		2.3	7	ns
Enable Time Z to Low	t <sub>PZL</sub>	Figures 4 and 5		2.3	7	ns
Maximum Operating Frequency (Note 11)	fMAX		400			MHz

Note 1: Maximum and minimum limits over temperature are guaranteed by design and characterization. Devices are 100% tested at  $T_A = +25^{\circ}C$ .

Note 2: Currents into the device are positive, and current out of the device is negative. All voltages are referenced to ground except VOD.

Note 3: Guaranteed by correlation data.

Note 4: AC parameters are guaranteed by design and characterization.

- Note 5: CL includes probe and jig capacitance.
- **Note 6:** Signal generator conditions for dynamic tests:  $V_{OL} = 0$ ,  $V_{OH} = 3V$ , f = 100MHz, 50% duty cycle,  $R_O = 50\Omega$ ,  $t_R \le 1$ ns,  $t_F \le 1$ ns (0% to 100%).

**Note 7:**  $t_{SKD1}$  is the magnitude difference of differential propagation delay.  $t_{SKD1} = lt_{PHLD} - t_{PLHD}l$ .

Note 8: t<sub>SKD2</sub> is the magnitude difference of t<sub>PHLD</sub> or t<sub>PLHD</sub> of one channel to the t<sub>PHLD</sub> or t<sub>PLHD</sub> of another channel on the same device.

Note 9: t<sub>SKD3</sub> is the magnitude difference of any differential propagation delays between devices at the same V<sub>CC</sub> and within 5°C of each other.

Note 10: t<sub>SKD4</sub> is the magnitude difference of any differential propagation delays between devices operating over the rated supply and temperature ranges.

**Note 11:**  $f_{MAX}$  signal generator conditions:  $V_{OL} = 0$ ,  $V_{OH} = 3V$ , f = 400MHz, 50% duty cycle,  $R_O = 50\Omega$ ,  $t_R \le 1$ ns,  $t_F \le 1$ ns (0% to 100%). Transmitter output criteria: duty cycle = 45% to 55%,  $V_{OD} \ge 250$ mV.

# MAX9123

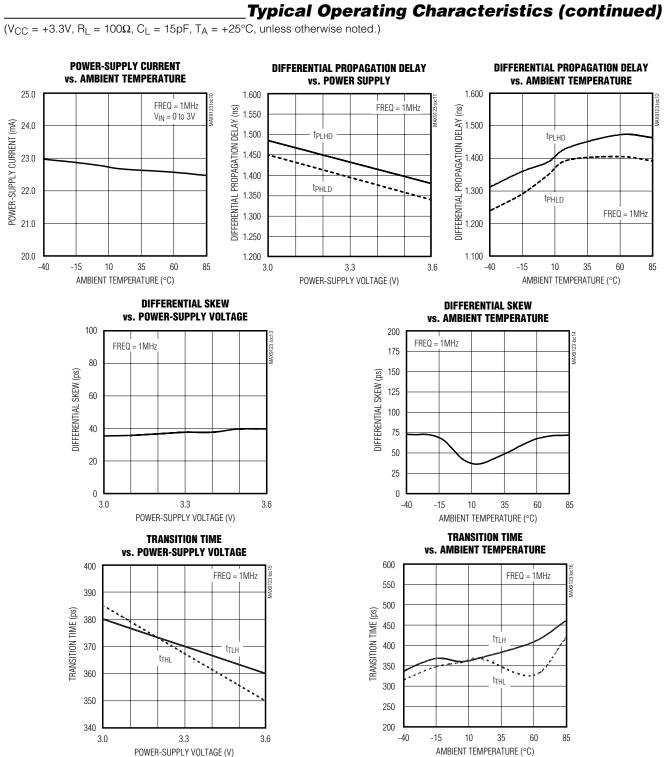
 $(V_{CC} = +3.3V, R_L = 100\Omega, C_L = 15pF, T_A = +25^{\circ}C, unless otherwise noted.)$ 

**MAX9123** 

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**OUTPUT LOW VOLTAGE OUTPUT HIGH VOLTAGE OUTPUT SHORT-CIRCUIT CURRENT** vs. POWER-SUPPLY VOLTAGE vs. POWER-SUPPLY VOLTAGE vs. POWER-SUPPLY VOLTAGE 1.100 -3.700 1.100 (W-3.695 -3.690 -3.685 -3.685 -3.680 -3.680 -3.680 -3.675 -3.675 -3.675 VIN = VCC OT GND (A) 1.098 1.096 1.096 1.094 1.098 OUTPUT LOW VOLTAGE (V) 1.096 1.094 1.092 1.092 1.090 1.090 -3.650 3.6 3.3 3.3 3.6 3.0 3.3 3.0 3.0 3.6 POWER-SUPPLY VOLTAGE (V) POWER-SUPPLY VOLTAGE (V) POWER-SUPPLY VOLTAGE (V) **OUTPUT HIGH-IMPEDANCE STATE CURRENT** DIFFERENTIAL OUTPUT VOLTAGE **DIFFERENTIAL OUTPUT VOLTAGE** vs. POWER-SUPPLY VOLTAGE vs. POWER SUPPLY vs. LOAD RESISTOR 0 390 600 OUTPUT HIGH-IMPEDANCE STATE CURRENT (pA)  $\dot{V}_{IN} = V_{CC}$  or 385 DIFFERENTIAL OUTPUT VOLTAGE (V) GND -50 380 375 -100 370 -150 365 360 -200 355 -250 350 300 3.0 3.3 3.6 3.6 3.0 3.3 90 100 110 120 130 140 150 POWER-SUPPLY VOLTAGE (V) LOAD RESISTOR  $(\Omega)$ POWER-SUPPLY VOLTAGE (V) **OFFSET VOLTAGE POWER-SUPPLY CURRENT POWER-SUPPLY CURRENT** vs. POWER-SUPPLY VOLTAGE vs. POWER-SUPPLY VOLTAGE vs. FREQUENCY 40 1.260 25.0  $V_{IN} = 0$  to 3VFREQ = 1MHz38  $V_{IN} = 0$  to 3VPOWER-SUPPLY CURRENT (mA) 1.256 35 OFFSET VOLTAGE (V) 33 1.252 30 1.248 28 ALL SWITCHING 25 1.244 23 ONE SWITCHING 1.240 20 20.0 3.0 3.0 3.3 3.6 0.1 10 100 3.3 3.6 1 1000 POWER-SUPPLY VOLTAGE (V) POWER-SUPPLY VOLTAGE (V) FREQUENCY (MHz)

# **Typical Operating Characteristics**



**MAX9123** 

**MAX9123** 

# \_Pin Description

Termination

PIN	NAME	FUNCTION				
1	1ENDriver Enable Input. The driver is disabled when EN is low. EN is internally pulled down high and $\overline{EN}$ = low or open, the outputs are active. For other combinations of EN and $\overline{EN}$ outputs are disabled and are high impedance.					
2, 3, 6, 7	IN_	LVTTL/LVCMOS Driver Inputs				
4	V <sub>CC</sub>	Power-Supply Input. Bypass $V_{CC}$ to GND with 0.1µF and 0.001µF ceramic capacitors.				
5	GND	Ground				
8 EN Driver Enable Input. The transmitter is disabled when EN is high. EN is internally pulled dow		Driver Enable Input. The transmitter is disabled when $\overline{EN}$ is high. $\overline{EN}$ is internally pulled down.				
9, 12, 13, 16	OUT	Inverting LVDS Driver Outputs				
10, 11, 14, 15	OUT_+	Noninverting LVDS Driver Outputs				

# **Detailed Description**

The LVDS interface standard is a signaling method intended for point-to-point communication over a controlled-impedance medium as defined by the ANSI/TIA/EIA-644 and IEEE 1596.3 standards. The LVDS standard uses a lower voltage swing than other common communication standards, achieving higher data rates with reduced power consumption while reducing EMI emissions and system susceptibility to noise.

The MAX9123 is an 800Mbps quad differential LVDS driver that is designed for high-speed, point-to-point, and low-power applications. This device accepts LVTTL/LVCMOS input levels and translates them to LVDS output signals.

The MAX9123 generates a 2.5mA to 4.0mA output current using a current-steering configuration. This currentsteering approach induces less ground bounce and no shoot-through current, enhancing noise margin and system speed performance. The driver outputs are shortcircuit current limited, and enter a high-impedance state when the device is not powered or is disabled.

The current-steering architecture of the MAX9123 requires a resistive load to terminate the signal and complete the transmission loop. Because the device switches current and not voltage, the actual output voltage swing is determined by the value of the termination resistor at the input of an LVDS receiver. Logic states are determined by the direction of current flow through the termination resistor. With a typical 3.7mA output current, the MAX9123 produces an output voltage of 370mV when driving a 100 $\Omega$  load.

Because the MAX9123 is a current-steering device, no output voltage will be generated without a termination resistor. The termination resistors should match the differential impedance of the transmission line. Output voltage levels depend upon the value of the termination resistor. The MAX9123 is optimized for point-to-point interface with 100 $\Omega$  termination resistors at the receiver inputs. Termination resistance values may range between 90 $\Omega$  and 132 $\Omega$ , depending on the characteristic impedance of the transmission medium.

### Table 1. Input/Output Function Table

ENA	BLES	INPUTS	OUTPUTS		
EN	ĒN	IN_	OUT_+	OUT	
Н	L or open	L	L	Н	
Н	L or open	Н	Н	L	
	ombinations BLE pins	Don't care	Z	Z	

# **Applications Information**

### **Power-Supply Bypassing**

Bypass V<sub>CC</sub> with high-frequency, surface-mount ceramic  $0.1\mu$ F and  $0.001\mu$ F capacitors in parallel as close to the device as possible, with the smaller valued capacitor closest to V<sub>CC</sub>.

### **Differential Traces**

Output trace characteristics affect the performance of the MAX9123. Use controlled-impedance traces to match trace impedance to the transmission medium.



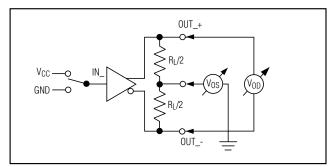


Figure 1. Driver VOD and VOS Test Circuit

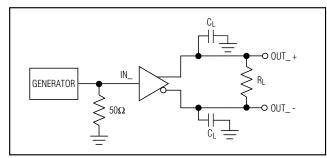


Figure 2. Driver Propagation Delay and Transition Time Test Circuit

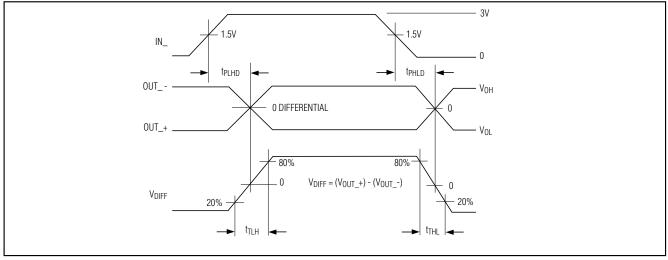


Figure 3. Driver Propagation Delay and Transition Time Waveforms

Eliminate reflections and ensure that noise couples as common mode by running the differential trace pairs close together. Reduce skew by matching the electrical length of the traces. Excessive skew can result in a degradation of magnetic field cancellation.

Maintain the distance between the differential traces to avoid discontinuities in differential impedance. Avoid 90° turns and minimize the number of vias to further prevent impedance discontinuities.

### **Cables and Connectors**

Transmission media should have a nominal differential impedance of  $100\Omega$ . To minimize impedance discontinuities, use cables and connectors that have matched differential impedance.

Avoid the use of unbalanced cables such as ribbon or simple coaxial cable. Balanced cables such as twisted pair offer superior signal quality and tend to generate less EMI due to canceling effects. Balanced cables tend to pick up noise as common mode, which is rejected by the LVDS receiver.

### **Board Layout**

**MAX9123** 

For LVDS applications, a four-layer PC board that provides separate power, ground, LVDS signals, and input signals is recommended. Isolate the LVTTL/LVCMOS and LVDS signals from each other to prevent coupling.

### Chip Information

TRANSISTOR COUNT: 1246 PROCESS: CMOS





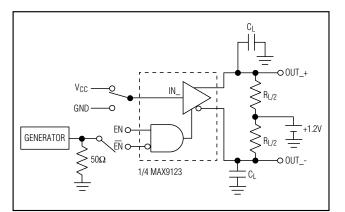
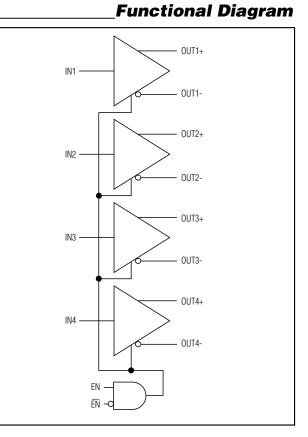


Figure 4. Driver High-Impedance Delay Test Circuit



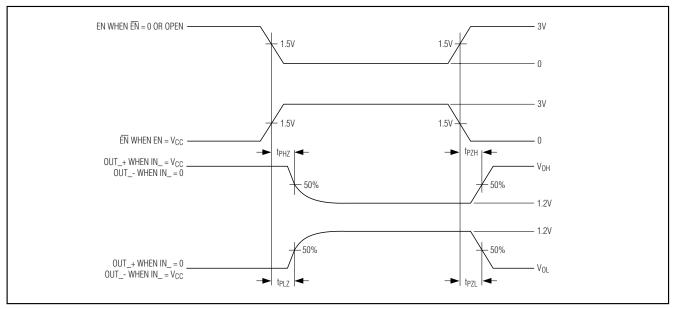


Figure 5. Driver High-Impedance Delay Waveform

# **Package Information**

